LP2980-ADJEP Micropower SOT, 50 mA Ultra Low-Dropout Adjustable Voltage Regulator

Check for Samples: LP2980-ADJEP

FEATURES

- **Ultra Low Dropout Voltage**
- **Output Adjusts From 1.23V to 15V**
- **Specified 50 mA Output Current**
- **Uses Tiny SOT Package**
- **Requires Few External Components**
- **<1 µA Quiescent Current When Shutdown**
- **Low Ground Pin Current at All Loads**
- **High Peak Current Capability (150 mA Typical)**
- **Wide Supply Voltage Range (2.5V–16V)**
- **Overtemperature/Overcurrent Protection**

APPLICATIONS

- **Selected Military Applications**
- **Selected Avionics Applications**

DESCRIPTION

The LP2980-ADJEP is a 50 mA adjustable voltage regulator designed to provide ultra low dropout in battery powered applications.

Using an optimized VIP™ (vertically Integrated PNP) process, the LP2980-ADJEP delivers unequalled performance in all specifications critical to battery-powered designs:

Adjustable Output: output voltage can be set from 1.23V to 15V.

Precision Reference: 0.75% tolerance.

Dropout Voltage: typically 120 mV @ 50 mA load, and 7 mV @ 1 mA load.

Ground Pin Current: typically 320 µA @ 50 mA load, and 80 µA @ 1 mA load.

Sleep Mode: less than 1 µA quiescent current when on/off pin is pulled low.

Smallest Possible Size: SOT package uses minimum board space.

ENHANCED PLASTIC

- Extended Temperature Performance of -40°C to +125°C
- Baseline Control - Single Fab & Assembly Site
- Process Change Notification (PCN)
- Qualification & Reliability Data
- Solder (PbSn) Lead Finish is standard
- Enhanced Diminishing Manufacturing Sources (DMS) Support

Connection Diagram

5-Lead Small Outline Package

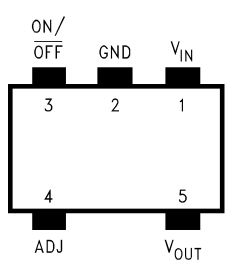

Figure 1. Top View
See Package Number DBV

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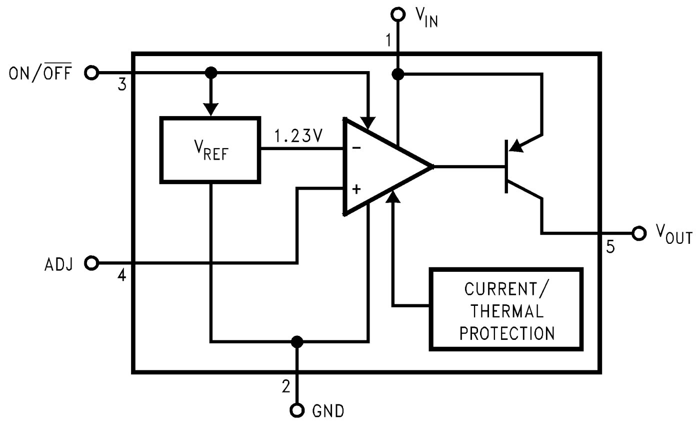
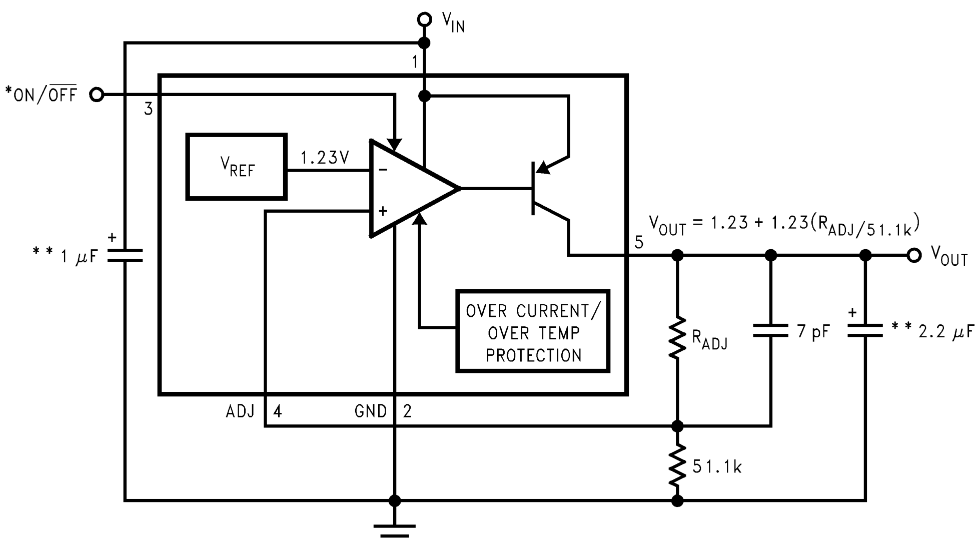
Block Diagram



Basic Application Circuit



*ON/OFF INPUT MUST BE ACTIVELY TERMINATED. TIE TO V_{IN} IF THIS FUNCTION IS NOT TO BE USED.
**MINIMUM CAPACITANCE IS SHOWN TO ENSURE STABILITY OVER FULL LOAD CURRENT RANGE (SEE APPLICATION HINTS).

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings[(1)(2)]

Storage Temperature Range	−65 to +150°C
Operating Junction Temperature Range	−40 to +125°C
Lead Temp. (Soldering, 5 seconds)	260°C
ESD Rating [(3)]	2 kV
Power Dissipation [(4)]	Internally Limited
Input Supply Voltage (Survival)	−0.3V to +16V
Input Supply Voltage (Operating)	2.5V to +16V
Shutdown Input Voltage (Survival)	−0.3V to +16V
Output Voltage (Survival) [(5)]	−0.3V to 16V
I_{OUT} (Survival)	Short Circuit Protected
Input-Output Voltage (Survival) [(6)]	−0.3V to 16V

(1) Absolute maximum ratings indicate limits beyond which damage to the component may occur. Electrical specifications do not apply when operating the device outside of its rated operating conditions.
(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
(3) The ESD rating of pins 3 and 4 is 1 kV.
(4) The maximum allowable power dissipation is a function of the maximum junction temperature, T_J(MAX), the junction-to-ambient thermal resistance, θ_{J-A}, and the ambient temperature, T_A. The maximum allowable power dissipation at any ambient temperature is calculated using: $P(MAX) = \frac{T_J(MAX) - T_A}{\theta_{J-A}}$ The value of θ_{J-A} for the SOT package is 300°C/W. Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown.
(5) If used in a dual-supply system where the regulator load is returned to a negative supply, the LP2980-ADJEP output must be diode-clamped to ground.
(6) The output PNP structure contains a diode between the V_{IN} and V_{OUT} terminals that is normally reverse-biased. Reversing the polarity from V_{IN} to V_{OUT} will turn on this diode (see Application Hints).

Electrical Characteristics[(1)]

Limits in standard typeface are for T_J = 25°C, and limits in **boldface type** apply over the full operating temperature range. Unless otherwise specified: V_{IN} = 4.3V, V_{OUT} = 3.3V, I_L = 1 mA, C_{IN} = 1 µF, C_{OUT} = 2.2 µF, $V_{ON/OFF}$ = 2V.

Symbol	Parameter	Conditions	Typ	LP2980I-ADJEP[(2)]		Units
				Min	Max	
V_{REF}	Reference Voltage		1.225	1.213	1.237	V
		1 mA < I_L < 50 mA V_{OUT} + 1 ≤ V_{IN} ≤ 16V	1.225	1.206 **1.182**	1.243 **1.268**	
$\Delta V_{REF}/\Delta V_{IN}$	Reference Voltage Line Regulation	2.5V ≤ V_{IN} ≤ 16V	3		6.0 **15.0**	mV
V_{IN}–V_O	Dropout Voltage [(3)]	I_L = 0	1		3 **5**	mV
		I_L = 1 mA	7		10 **15**	
		I_L = 10 mA	40		60 **90**	
		I_L = 50 mA	120		150 **225**	

(1) Testing and other quality control techniques are used to the extent deemed necessary to ensure product performance over the specified temperature range. Product may not necessarily be tested across the full temperature range and all parameters may not necessarily be tested. In the absence of specific PARAMETRIC testing, product performance is assured by characterization and/or design.
(2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are specified through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate TI's Average Outgoing Quality Level (AOQL).
(3) Dropout voltage is defined as the input to output differential at which the output voltage drops 100 mV below the value measured with a 1V differential.

Electrical Characteristics[1] (continued)

Limits in standard typeface are for T_J = 25°C, and limits in **boldface type** apply over the full operating temperature range. Unless otherwise specified: V_{IN} = 4.3V, V_{OUT} = 3.3V, I_L = 1 mA, C_{IN} = 1 µF, C_{OUT} = 2.2 µF, $V_{ON/OFF}$ = 2V.

Symbol	Parameter	Conditions	Typ	LP2980I-ADJEP[2]		Units
				Min	Max	
I_{GND}	Ground Pin Current	I_L = 0	60		95 **125**	µA
		I_L = 1 mA	80		110 **170**	
		I_L = 10 mA	120		220 **460**	
		I_L = 50 mA	320		600 **1200**	
		$V_{ON/OFF}$ < 0.18V	0.01		**1**	
I_{ADJ}	ADJ Pin Bias Current	1 mA ≤ I_L ≤ 50 mA	150		350	nA
$V_{ON/OFF}$	ON/OFF Input Voltage [4]	High = O/P ON	1.4	**1.6**		V
		Low = O/P OFF	0.55		**0.18**	
$I_{ON/OFF}$	ON/OFF Input Current	$V_{ON/OFF}$ = 0	0.01		**−1**	µA
		$V_{ON/OFF}$ = 5V	5		**15**	
I_O(PK)	Peak Output Current	V_{OUT} ≥ V_O(NOM) − 5%	150	100		mA
e_n	Output Noise Voltage (RMS)	BW = 300 Hz to 50 kHz, C_{OUT} = 10 µF	160			µV
$\Delta V_{OUT}/\Delta V_{IN}$	Ripple Rejection	f = 1 kHz C_{OUT} = 10 µF	68			dB
I_O(MAX)	Short Circuit Current	R_L = 0 (Steady State)[5]	150			mA

(4) The ON/OFF input must be properly driven to prevent possible misoperation. For details, refer to Application Hints.
(5) See Typical Performance Characteristics.

Typical Performance Characteristics

Unless otherwise specified: T_A = 25°C, V_{IN} = V_O(NOM) + 1V, I_L = 1 mA, ON/OFF pin tied to V_{IN}, R_{ADJ} = 86.6k, and test circuit is as shown in Basic Application Circuit.

Output Voltage vs. Temperature

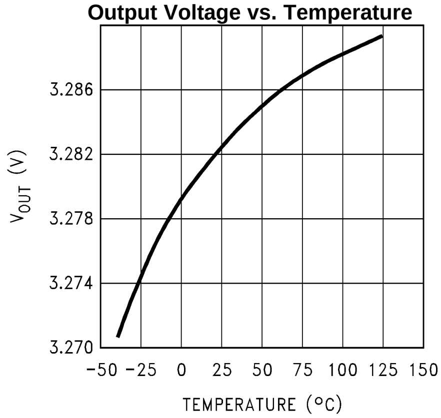


Figure 2.

Dropout Characteristics

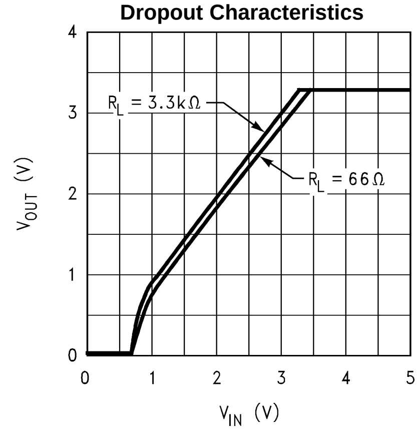


Figure 3.

Dropout Voltage vs. Temperature

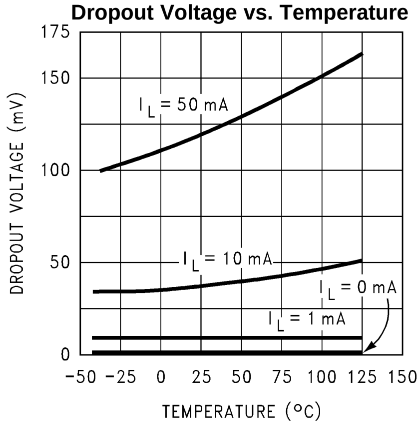


Figure 4.

Dropout Voltage vs. Load Current

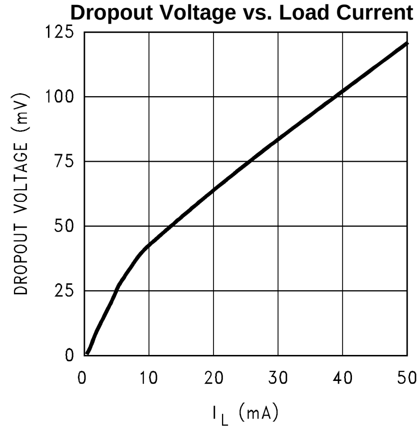


Figure 5.

Ground Pin Current vs. Temperature

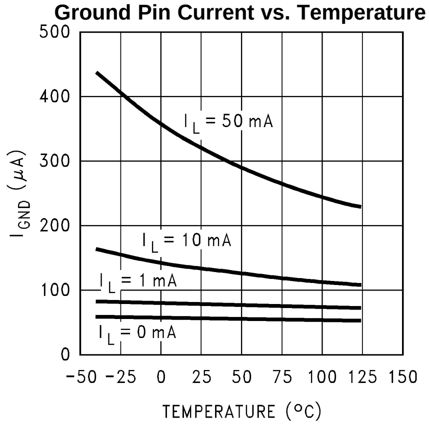


Figure 6.

Ground Pin Current vs. Load Current

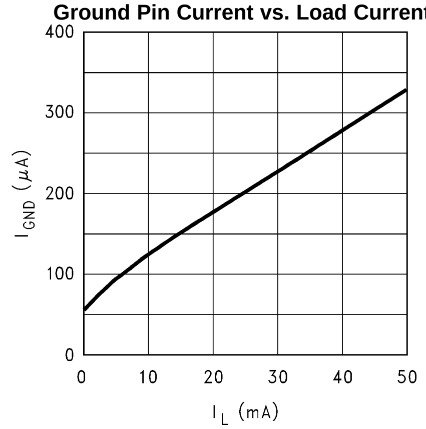


Figure 7.

Typical Performance Characteristics (continued)

Unless otherwise specified: T_A = 25°C, V_{IN} = V_O(NOM) + 1V, I_L = 1 mA, ON/OFF pin tied to V_{IN}, R_{ADJ} = 86.6k, and test circuit is as shown in Basic Application Circuit.

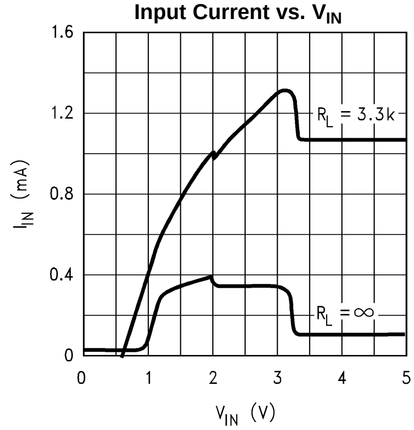


Figure 8.

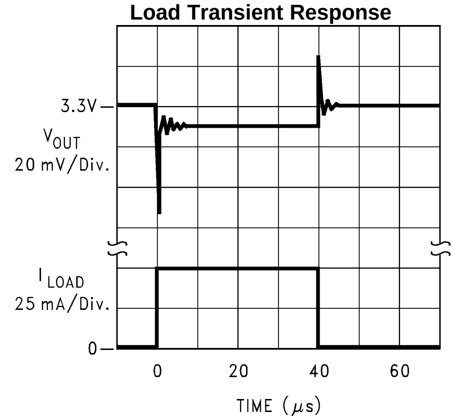


Figure 9.

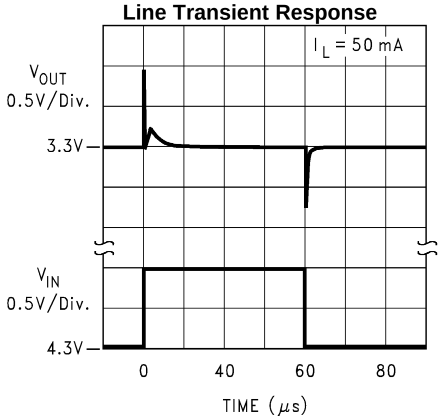


Figure 10.

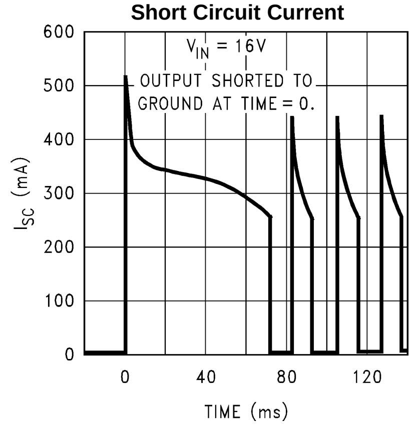


Figure 11.

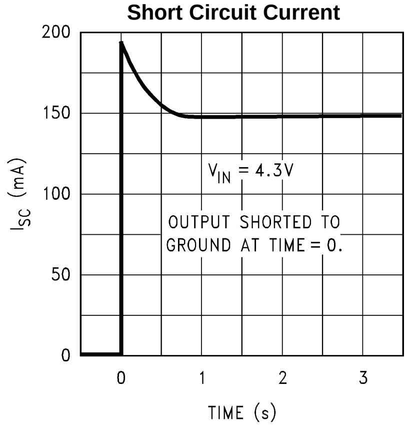


Figure 12.

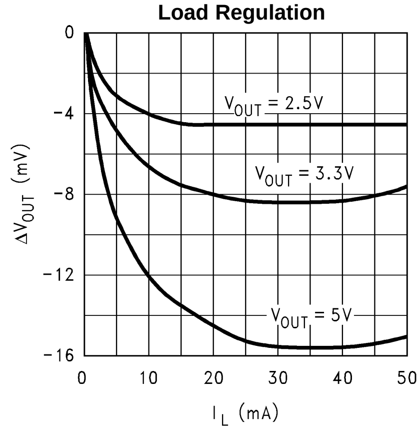


Figure 13.

Typical Performance Characteristics (continued)

Unless otherwise specified: T_A = 25°C, V_{IN} = V_O(NOM) + 1V, I_L = 1 mA, ON/OFF pin tied to V_{IN}, R_{ADJ} = 86.6k, and test circuit is as shown in Basic Application Circuit.

ADJ Pin Bias Current vs. Load Current

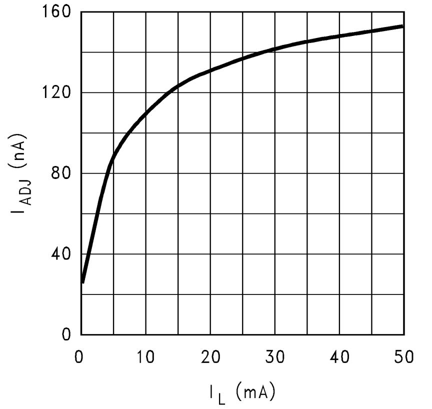


Figure 14.

ADJ Pin Bias Current vs. Temperature

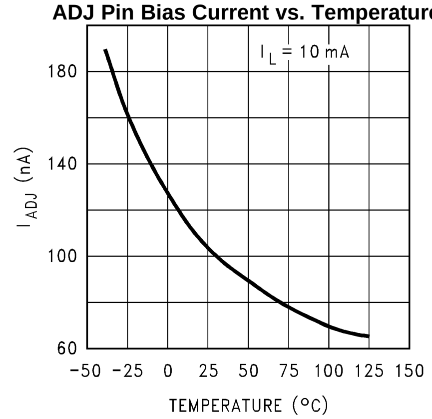


Figure 15.

ON/OFF Threshold vs.Temperature

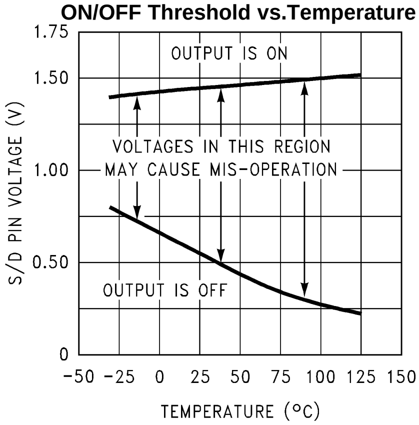


Figure 16.

Output Noise Density

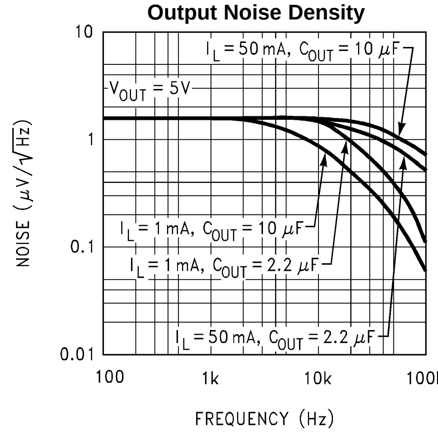


Figure 17.

Ripple Rejection

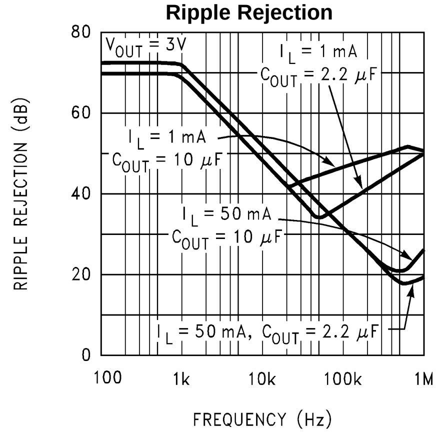


Figure 18.

APPLICATION HINTS

External Capacitors

Like any low-dropout regulator, the external capacitors must be selected carefully to assure regulator loop stability.

INPUT CAPACITOR: An input capacitor whose value is ≥1 μF is *required* (the amount of capacitance may be increased without limit).

Any good quality Tantalum or Ceramic capacitor may be used here. The capacitor must be located not more than 0.5″ from the input pin and returned to a clean analog ground.

OUTPUT CAPACITOR: The output capacitor must meet both the requirement for minimum amount of capacitance and E.S.R. (Equivalent Series Resistance) for stable operation.

Curves are provided below which show the allowable ESR of the output capacitor as a function of load current for both 2.2 μF and 4.7 μF. A solid Tantalum capacitor is the best choice for the output.

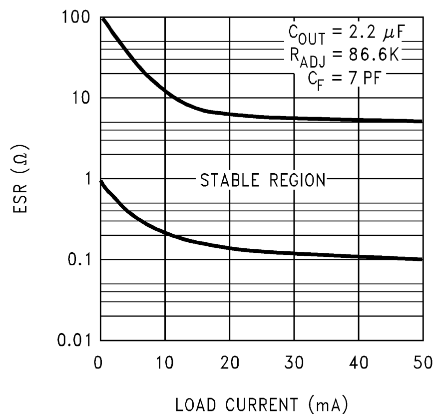


Figure 19. 2.2 μF ESR Curves

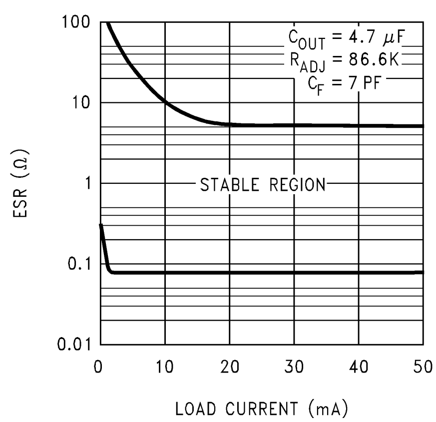


Figure 20. 4.7 μF ESR Curves

IMPORTANT: The output capacitor must maintain its ESR in the stable region *over the full operating temperature range* to assure stability. Also, capacitor tolerance and variation with temperature must be considered to assure the minimum amount of capacitance is provided at all times.

Note that this capacitor must be located not more than 0.5” from the output pin and returned to a clean analog ground.

FEED-FORWARD CAPACITOR: A 7 pF feed-forward capacitor is required (see Basic Application Circuit). The function of this capacitor is to provide the lead compensation necessary for loop stability.

A temperature-stable ceramic capacitor (type NPO or COG) should be used here.

Capacitor Characteristics

TANTALUM: The best capacitor choice for the LP2980-ADJEP output is solid Tantalum. The ESR of a good quality Tantalum is almost perfectly centered in the middle of the "stable" range of the ESR curve (about 0.5Ω–1Ω).

The temperature stability of Tantalums is typically very good, with a total variation of only about 2:1 over the temperature range of −40°C to +125°C (ESR increases at colder temperatures).

Off-brand capacitors should be avoided, as some poor quality Tantalums are seen with ESR's > 10Ω, and this usually causes oscillation problems.

One caution about Tantalums if they are used on the input: the ESR of a Tantalum is low enough that it can be destroyed by surge current if powered up from a low impedance source (like a battery) that has no limit on inrush current. In these cases, use a ceramic input capacitor which does not have this problem.

CERAMIC: Ceramics are generally larger and more costly than Tantalums for a given amount of capacitance. Also, they have a very low ESR which is quite stable with temperature.

Be warned that the ESR of a ceramic capacitor is typically low enough to make an LDO oscillate: a 2.2 µF ceramic demonstrated an ESR of about 15 mΩ when tested. If used as an output capacitor, this will cause instability (see Figure 19 and Figure 20).

If a ceramic is used on the output of an LDO, a small resistance (about 1Ω) should be placed in series with the capacitor. If it is used as an input capacitor, no resistor is needed as there is no requirement for ESR on capacitors used on the input.

External Resistors

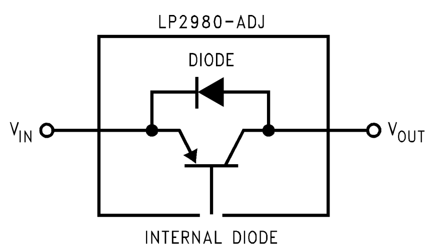
The output voltage is set using two external resistors (see Basic Application Circuit). It is recommended that the resistor from the ADJ pin to ground be 51.1k.

The other resistor (R_{ADJ}) which connects between V_{OUT} and the ADJ pin is selected to set V_{OUT} as given by the formula:

$$V_{OUT} = 1.23 + 1.23\ (R_{ADJ}/51.1k) \qquad (1)$$

Reverse Current Path

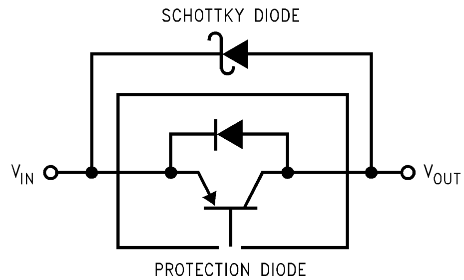
The power transistor used in the LP2980-ADJEP has an inherent diode connected between the input and output pin (see below).



If the output is forced above the input by more than a V_{BE}, this diode will become forward biased and current will flow into the output pin and out the input pin. This current must be limited to < 100 mA to prevent damage to the part.

The internal diode can also be turned on if the input voltage is abruptly stepped down to a voltage which is a V_{BE} below the output voltage. To prevent mis-operation, an external Schottky diode (see below) must be used in applications where the internal diode may be turned on.

Since the external Schottky diode turns on at a lower voltage than the internal diode, the Schottky conducts all of the current and prevents the internal diode from becoming forward biased.



ON/OFF Input Operation

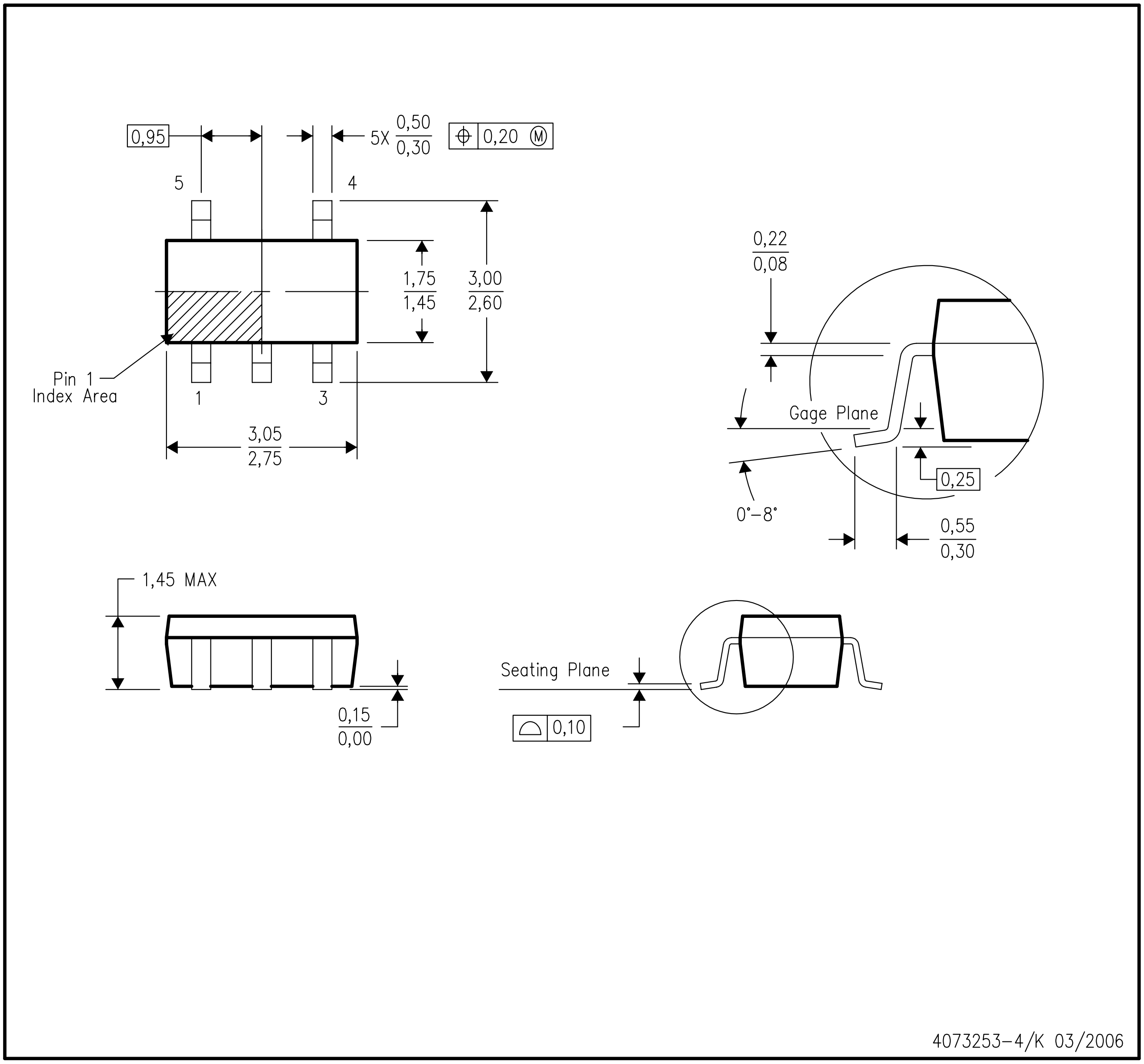
The LP2980-ADJEP is shut off by driving the ON/OFF input low, and turned on by pulling the ON/OFF input high. If this feature is not to be used, the ON/OFF input must be tied to V_{IN} to keep the regulator output on at all times (the ON/OFF input must not be left floating).

To ensure proper operation, the signal source used to drive the ON/OFF input must be able to swing above and below the specified turn-on/turn-off voltage thresholds which ensure an ON or OFF state (see Electrical Characteristics).

It is also important that the turn-on (and turn-off) voltage signals applied to the ON/OFF input have a slew rate which is greater than 40 mV/µs.

IMPORTANT: The shutdown function will not operate correctly if a slow-moving signal is used to drive the S/D input.

DBV (R-PDSO-G5) PLASTIC SMALL-OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Falls within JEDEC MO-178 Variation AA.

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